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Field Device Integration (FDI®) - Part 5: FDI Information Model (IEC 62769-5:2023)

Feldgeräteintegration (FDI®) - Teil 5: FDI-Informationsmodell (IEC 62769-5:2023)

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European foreword

The text of document 65E/858/CDV, future edition 3 of IEC 62769-5, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-5:2023.

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IEC 62541-7	NOTE	Approved as EN IEC 62541-7

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 61784-1-3	2023	Industrial networks - Profiles - Part 1-3: Fieldbus profiles - Communication Profile Family 3	EN IEC 61784-1-3	2023
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 61804-4	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 4: EDD interpretation	EN IEC 61804-4	-
IEC 62541-3	-	OPC Unified Architecture - Part 3: Address Space Model	EN IEC 62541-3	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN IEC 62541-4	-
IEC 62541-5	-	OPC Unified Architecture - Part 5: Information Model	EN IEC 62541-5	-
IEC 62541-6	-	OPC Unified Architecture - Part 6: Mappings	EN IEC 62541-6	-
IEC 62541-8	-	OPC Unified Architecture - Part 8: Data Access	EN IEC 62541-8	-
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	-
IEC 62769-1	-	Field Device Integration (FDI®) - Part 1: Overview	EN IEC 62769-1	-
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	EN IEC 62769-2	-
IEC 62769-3	-	Field Device Integration (FDI®) - Part 3: Server	EN IEC 62769-3	-
IEC 62769-4	-	Field Device Integration (FDI®) - Part 4: FDI Packages	EN IEC 62769-4	-
IEC 62769-6	-	Field Device Integration (FDI®) - Part 6: FDI Technology Mappings	EN IEC 62769-6	-
IEC 62769-7	-	Field Device Integration (FDI®) - Part 7: Communication Devices	EN IEC 62769-7	-

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IEC 62769-1xx	series	Field device integration (FDI®) - Part 1xx-y: Profiles	-	-
OPC 10000-19	-	OPC Unified Architecture - Part 19: Dictionary Reference	-	-

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FIELD DEVICE INTEGRATION (FDI®) –

Part 5: FDI® Information Model

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This edition includes the following significant technical changes with respect to the previous edition:

a) added INTERACTIVE_TRANSFER_TO_DEVICE ACTION.

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The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI®)*, can be found on the IEC website.

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